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TEST REPORT

CHOMERICS THERMFLOW®
T557 Tested with Voids

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Chomerics Approved Signatory:

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1. **INTRODUCTION**
   a. The impact of voids or missing material on thermal impedence of T577 was examined

2. **METHOD**
   a. A metal probe was use to make holes/voids in T557 pads. Three samples were generated, one with no voids, one with small voids and one with large voids. Pictures on the pads can be seen below, Figure 1.

   b. Thermal impedence was measured per a modified ASTM 5470. The test pressure was 50 PSI and the test temperature was 70°C. Two samples were tested for each void size.

3. **RESULTS**
   There is no difference in thermal impedence for the samples tested as shown in Table 1.

Table 1. Thermal Impedence

	Sample 1	Sample 2	Sample 3
Test 1 Thermal Impedence (C*in^2/W)	0.024	0.021	0.025
Test 2 Thermal Impedence (C*in^2/W)	0.022	0.024	0.023

Figure 1. Picture of Samples with Voids